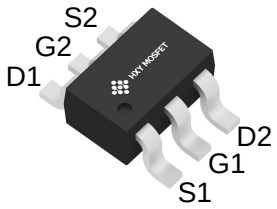
SI3439KDWA-TP

Dual N+P-Channel Enhancement Mode MOSFET

Description

The SI3439KDWA-TP uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOT-363

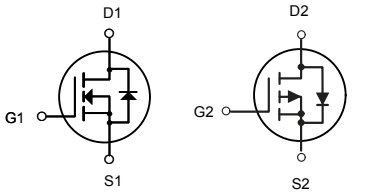
General Features

V_{DS} = 20V I_D =0.75A

$R_{DS(ON)}$ < 380mΩ @ V_{GS}=4.5V

V_{DS} = -20V I_D =-0.66A

$R_{DS(ON)}$ < 570mΩ @ V_{GS}=-4.5V



N-Channel MOSFET P-Channel MOSFET

Application

Wireless charging

Boost driver

Brushless motor

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SI3439KDWA-TP	SOT-363	HXY MOSFET	3000

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
VDS	Drain-Source Voltage	20	-20	V
VGS	Gate-Source Voltage	±12	±12	V
I_D@T_A=25°C	Continuous Drain Current, V_{GS} @ 10V[1]	0.75	-0.66	A
IDM	Pulsed Drain Current[2]	1.8	-1.2	A
TSTG	Storage Temperature Range	-55 to 150	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C
$R_{\theta}JA$	Thermal Resistance Junction-Ambient [1]	833		°C/W

N-ch MOSFET Electrical Characteristics (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characterisitcs						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	20			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =20V,V_{GS} = 0V			1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±10V, V_{DS} = 0V			±20	uA
Gate threshold voltage (note 2)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	0.35		1.1	V
Drain-source on-resistance(note 2)	$R_{DS(on)}$	V_{GS} =4.5V, I_D =0.65A		210	380	mΩ
		V_{GS} =2.5V, I_D =0.55A		320	450	mΩ
		V_{GS} =1.8V, I_D =0.45A		390	800	mΩ
Forward tranconductance(note 2)	g_{FS}	V_{DS} =10V, I_D =0.8A		1.6		S
Diode forward voltage	V_{SD}	I_S=0.15A, V_{GS} = 0V			1.2	V
Dynamic Characteristics (note 4)						
Input Capacitance	C_{iss}	V_{DS} =16V,V_{GS} =0V,f =1MHz		79	120	pF
Output Capacitance	C_{oss}			13	20	pF
Reverse Transfer Capacitance	C_{rss}			9	15	pF
Switching Characteristics (note 3,4)						
Turn-on delay time	$t_{d(on)}$	V_{GS}=4.5V,V_{DS}=10V, I_D=500mA,R_{GEN}=10Ω		6.7		ns
Turn-on rise time	t_r			4.8		ns
Turn-off delay time	$t_{d(off)}$			17.3		ns
Turn-off fall time	t_f			7.4		ns

P-ch MOSFET Electrical Characteristics (T_a=25℃ unless otherwise noted)

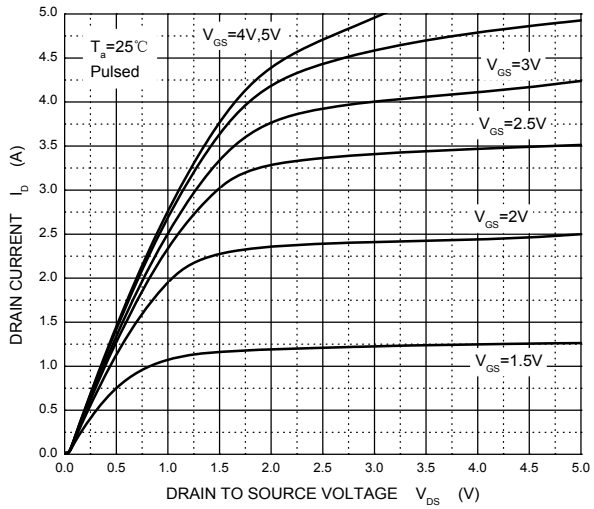
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =-250μA	-20			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =-20V,V_{GS} = 0V			-1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±10V, V_{DS} = 0V			±20	uA
Gate threshold voltage (note 2)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =-250μA	-0.35		-1.1	V
Drain-source on-resistance(note 2)	$R_{DS(on)}$	V_{GS} =-4.5V, I_D =-1A		430	570	mΩ
		V_{GS} =-2.5V, I_D =-0.8A		624	700	mΩ
		V_{GS} =-1.8V, I_D =-0.5A		950		mΩ
Forward tranconductance(note 2)	g_{FS}	V_{DS} =-10V, I_D =-0.54A		1.2		S
Diode forward voltage	V_{SD}	I_S=-0.5A, V_{GS} = 0V			-1.2	V
Dynamic Characteristics (note 4)						
Input Capacitance	C_{iss}	V_{DS} =-16V,V_{GS} =0V,f =1MHz		113	170	pF
Output Capacitance	C_{oss}			15	25	pF
Reverse Transfer Capacitance	C_{rss}			9	15	pF
Switching Characteristics (note 3, 4)						
Turn-on delay time	$t_{d(on)}$	V_{GS}=-4.5V,V_{DS}=-10V, I_D=-200mA,R_{GEN}=10Ω		9		ns
Turn-on rise time	t_r			5.8		ns
Turn-off delay time	$t_{d(off)}$			32.7		ns
Turn-off fall time	t_f			20.3		ns

Notes :

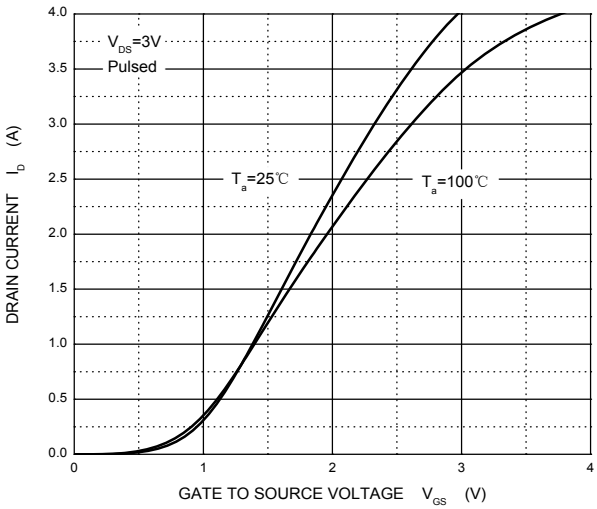
1.Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300μs, duty cycle≤2%.
3. Switching characteristics are independent of operating junction temperature.
4. Graranted by design，not subject to producting.

N-Channel Typical Characteristics

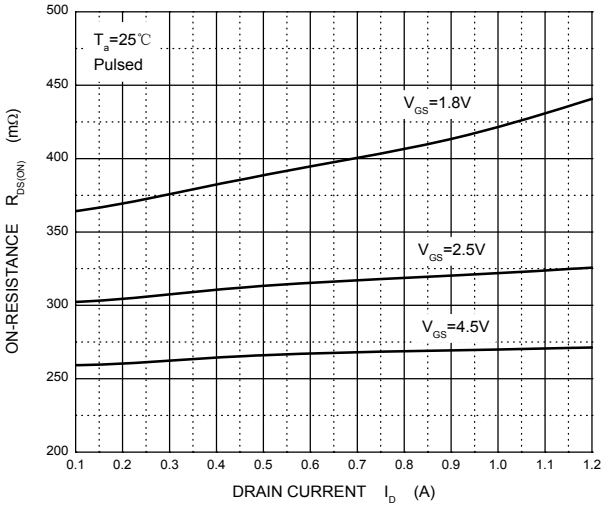
Output Characteristics



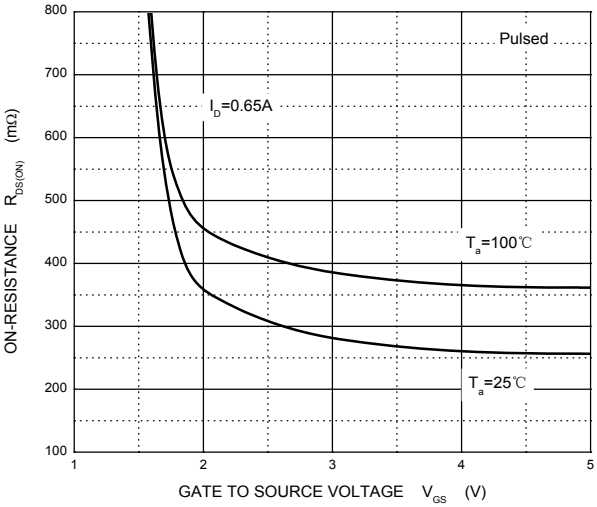
Transfer Characteristics



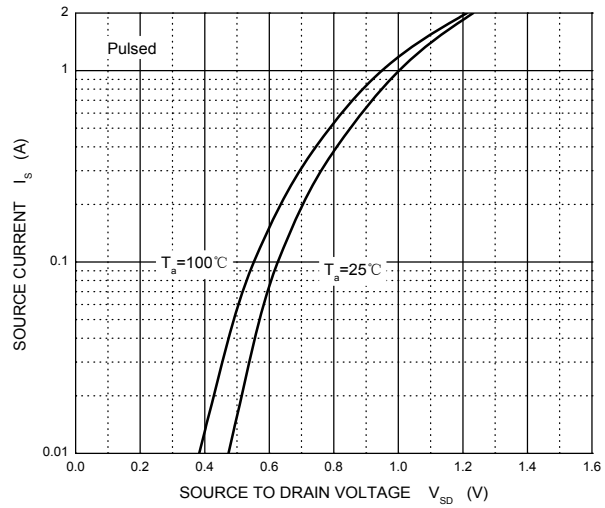
$R_{DS(ON)}$ — I_D



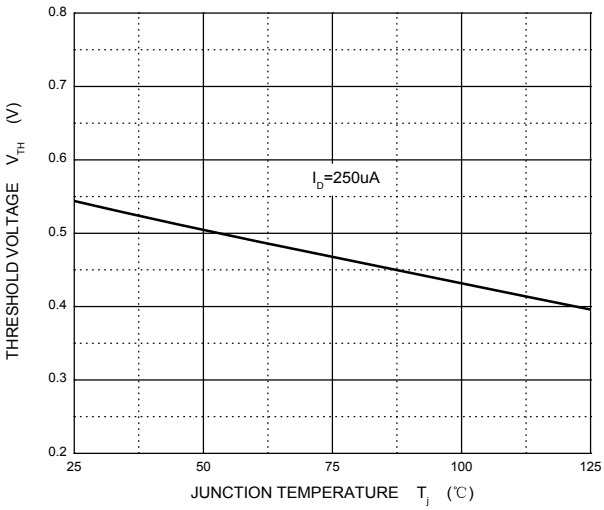
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}

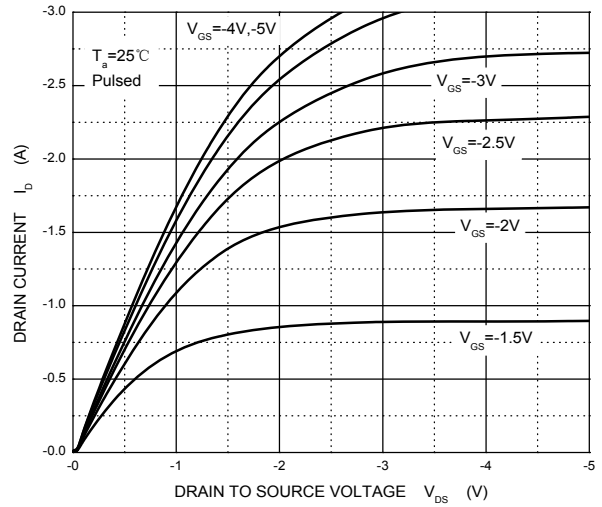


Threshold Voltage

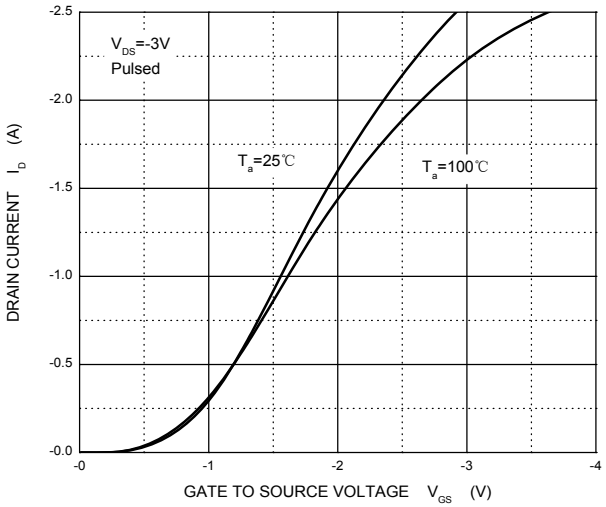


P-Channel Typical Characteristics

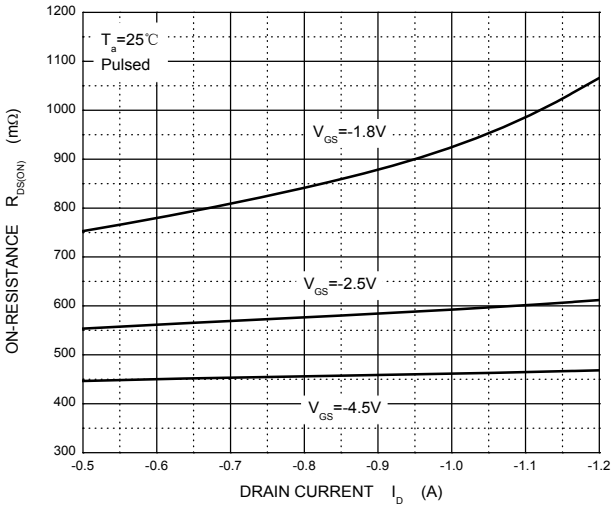
Output Characteristics



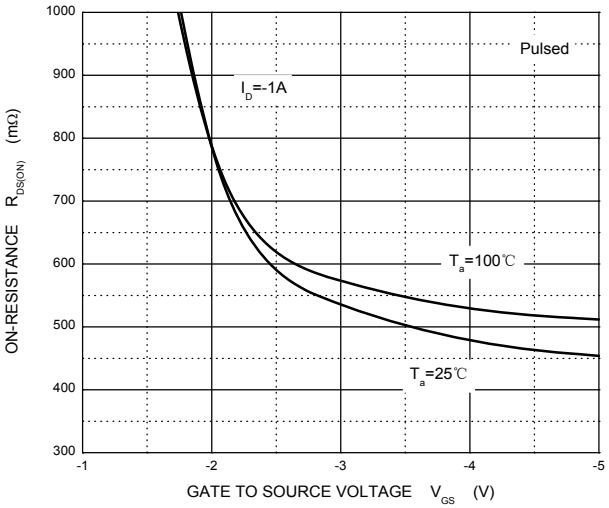
Transfer Characteristics



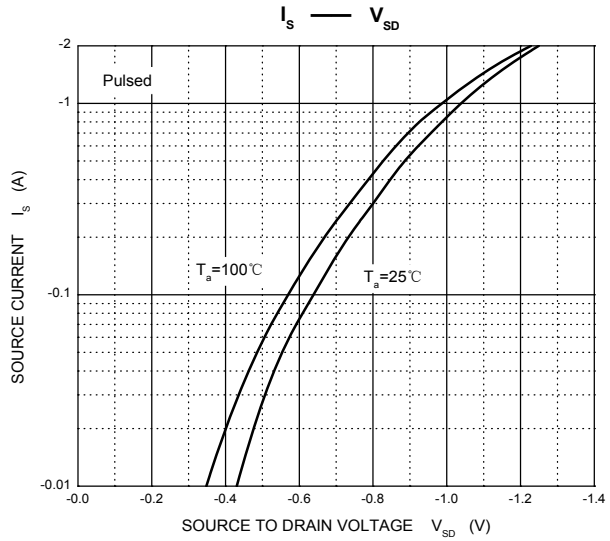
$R_{DS(ON)}$ — I_D



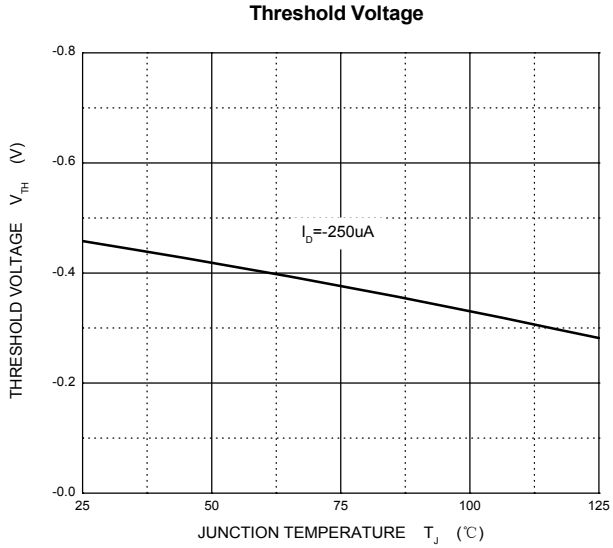
$R_{DS(ON)}$ — V_{GS}



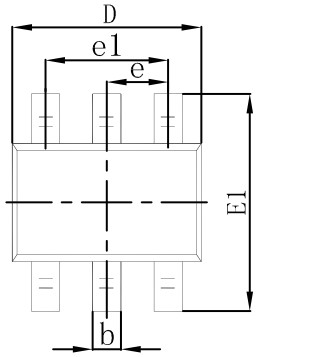
I_S — V_{SD}

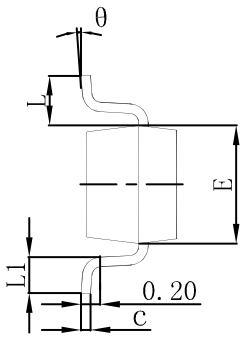


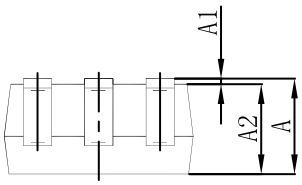
Threshold Voltage



SOT-363 Package Outline Dimensions

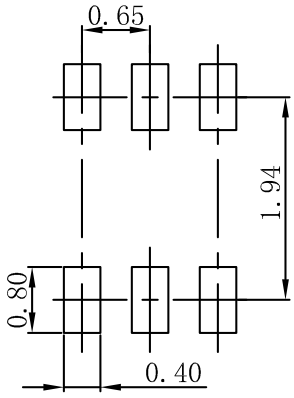






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

SOT-363 Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Attention

■ Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.

■ HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.

■ Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer’s products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer’s products or equipment.

■ HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could
give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

■ In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

■ Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

■ Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.